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Dkt No. 2002-0982/N1085-131
Application No. 10/813,799**REMARKS**

Claims 1-16 are pending and stand rejected. This paper amends claims 1 and 12-14.

Reconsideration of this application is respectfully requested.

The drawings stand objected to under 37 CFR 1.83(a) because the particles recited in claims 1 and 14 are not shown in the drawings. Therefore, submitted herewith for the Examiner's review and approval is a replacement drawing sheet which amends FIG. 1 to show the particles denoted by reference character 16. The specification has been correspondingly amended to include reference character 16. No new matter is believed entered by these amendments.

Claim 12 stands objected to because it depends from itself. In response, claim 12 has been amended to depend from claim 11.

Claims 1-7 and 10-16 stand rejected under 35 U.S.C. 103(a) as being unpatentable over U.S. Patent 7,006,205 to Agarwal et al. (Agarwal) in view of U.S. Patent 6,024,831 to Hwang et al. (Hwang).

The body of independent claims 1 and 14 have each been amended to recite "...exciting the particles generated by the reaction by-product film peeling from the interior wall of the reaction chamber of the semiconductor fabrication apparatus to emit light ..." to ensure that the "particles generated by a reaction by-product film peeling..." feature recited in the preamble of independent claims 1 and 14, is duly considered.

Agarwal in view of Hwang fail to teach or suggest a method of in situ monitoring of particles generated by a reaction by-product film peeling from an interior wall of a reaction chamber of a semiconductor fabrication apparatus to determine reaction chamber condition. Moreover, Agarwal in view of Hwang fail to teach or suggest the step of exciting the particles generated by the reaction by-product film peeling from the interior wall of the reaction chamber of the semiconductor fabrication apparatus to emit light"

In contrast, Agarwal in view of Hwang merely teach a method for event detection in a plasma process wherein optical emission data obtained from plasma particles coming into

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contact with a substrate is analyzed to determine the specific species in the plasma (see Agarwal, column 5, lines 58-65).

Hence, claims 1 and 14 are allowable over Agarwal in view of Hwang. Dependent claims 2-7, 10-13 and 15-16 are allowable over Agarwal in view of Hwang for at least the same reasons as stated for claims 1 and 14.

In view of the foregoing, withdrawal of this rejection is respectfully urged.

Claims 8 and 9 stand rejected under 35 U.S.C. 103(a) as being unpatentable over Agarwal in view of Hwang as applied to claims 1 and 7 above, and further in view of U.S. Patent 6,815,362 to Wong et al. (Wong).

Claims 9 and 8 include the features of respective claims 1 and 7. As discussed above, Agarwal in view of Hwang fail to teach or suggest the subject matter now recited in independent claims 1 and 7. Wong fails to cure the deficiencies of Agarwal in view of Hwang, as Wong is only concerned with determining an endpoint of an in-situ cleaning process of a semiconductor processing chamber, and not with in situ monitoring of particles generated by a reaction by-product film peeling from an interior wall of a reaction chamber of a semiconductor fabrication apparatus to determine reaction chamber condition, as claimed. Thus, claims 8 and 9 are allowable over Agarwal in view of Hwang and further in view of Wong.

In view of the foregoing, withdrawal of this rejection is respectfully urged.

Favorable reconsideration of this application is respectfully requested as it is believed that all outstanding issues have been addressed herein and, further, that claims 1-16 are in condition for allowance. Should there be any questions or matters whose resolution may be advanced by a telephone call, the examiner is cordially invited to contact applicants' undersigned attorney at his number listed below.

PETITION FOR EXTENSION OF TIME UNDER 37 CFR 1.136(a)

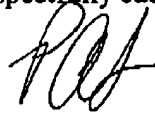
This is a request under the provisions of 37 CFR 1.136(a) to extend the period for filing a reply in the above identified application. The requested extension is one (1) month.

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The fee for the requested extension of time is \$120. The Commissioner is hereby authorized to charge payment of this fee to Deposit Account No. 04-1679.

The Commissioner is also authorized to charge any payment required under 37 CFR 1.16 and any patent application processing fees under 37 CFR 1.17, which are associated with this paper, or credit any overpayment to Deposit Account No. 04-1679.

Respectfully submitted,



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